

Application Serial No. 10/632,273
Response to September 7, 2004 OA

MI22-2379

In the Claims

CLAIMS

Claims 1-30 (Canceled).

31. (Currently amended) An engagement probe formed from a semiconductor material, and having comprising:

a substrate;

a projection supported over the substrate and comprising material of the substrate;
and

a grouping of a plurality of projecting apexes extending from the projection and
positioned is in sufficient proximity to one another to collectively engage a single
conductive pad on a semiconductor substrate.

32. (Previously presented) The engagement probe of claim 31 comprising a plurality of such groupings for engaging multiple conductive pads on the semiconductor substrate.

33.. (Previously presented) The engagement probe of claim 31 wherein the apexes are in the shape of multiple knife-edge lines.

Application Serial No. 10/632,273
Response to September 7, 2004 OA

MI22-2379

34. (Previously presented) The engagement probe of claim 31 wherein the apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines being positioned to form at least one polygon.

35. (Previously presented) The engagement probe of claim 31 wherein the apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines being positioned to form at least two polygons one of which is received entirely within the other.

36. (Currently amended) The engagement probe of claim 31 wherein the grouping of apexes is formed on a the projection which is supported by another projection, the another projection extending directly from a the substrate.

37. (Previously presented) The engagement probe of claim 31 wherein the apexes have a selected projecting distance, the projecting distance being about one-half the thickness of the conductive pad which the apparatus is adapted to engage.

38. (Currently amended) The engagement probe of claim 31 wherein the apexes project from a common plane of the projection, the apexes having respective tips and bases, the bases of adjacent projecting apexes being spaced from one another to define a penetration stop plane therebetween.

Application Serial No. 10/632,273
Response to September 7, 2004 OA

MI22-2379

39. (Currently amended) The engagement probe of claim 31 wherein the apexes project from a common plane of the projection, the apexes having respective tips and bases, the bases of adjacent projecting apexes being spaced from one another to define a penetration stop plane therebetween, the tips being a distance from the penetration stop plane of about one-half the thickness of the conductive pad which the apparatus is adapted to engage.

40. (Previously presented) The engagement probe of claim 31 wherein the apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines interconnecting to form at least one fully enclosed polygon.

41. (Previously presented) The engagement probe of claim 31 wherein outermost portions of the electrically conductive apexes constitute a first electrically conductive material, and wherein the conductive pads for which the probe is adapted have outermost portions constituting a second electrically conductive material; the first and second electrically conductive materials being different.

42. (New) An engagement probe formed from a semiconductor material and having a grouping of a plurality of projecting apexes positioned in sufficient proximity to one another to collectively engage a single conductive pad on a semiconductor substrate; and wherein the apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines being positioned to form at least one polygon.

**Application Serial No. 10/632,273
Response to September 7, 2004 OA**

MI22-2979

43. (New) An engagement probe formed from a semiconductor material and having a grouping of a plurality of projecting apexes positioned in sufficient proximity to one another to collectively engage a single conductive pad on a semiconductor substrate; and wherein the apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines being positioned to form at least two polygons one of which is received entirely within the other.

44. (New) An engagement probe formed from a semiconductor material and having a grouping of a plurality of projecting apexes positioned in sufficient proximity to one another to collectively engage a single conductive pad on a semiconductor substrate; and wherein the apexes are in the shape of multiple knife-edge lines, the multiple knife-edge lines interconnecting to form at least one fully enclosed polygon.

45. (New) The engagement probe of claim 31 wherein the plurality of the projecting apexes extend from a substantially planar uppermost surface of the projection.

46. (New) The engagement probe of claim 31 wherein an entirety of the projection is spaced from the substrate.

47. (New) The engagement probe of claim 31 wherein the substrate comprises bulk silicon.

**Application Serial No. 10/632,273
Response to September 7, 2004 OA**

MI22-2379

48. (New) The engagement probe of claim 31 wherein the projection comprises a lateral dimension less than a lateral dimension of the substrate.